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Semiconductor package

Abstract

A semiconductor package may include a redistribution substrate, a connection terminal, and a semiconductor chip sequentially stacked. The redistribution substrate may include an insulating layer, a plurality of redistribution patterns, which are vertically stacked in the insulating layer, and each of which includes interconnection and via portions, and a bonding pad on the interconnection portion of the topmost redistribution pattern. The topmost redistribution pattern and the bonding pad may include different metallic materials. The bonding pad may have first and second surfaces opposite to each other. The first surface of the bonding pad may be in contact with a top surface of the interconnection portion of the topmost redistribution pattern. A portion of the second surface of the bonding pad may be in contact with the connection terminal. The insulating layer may be extended to be in contact with the remaining portion of the second surface.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATIONS

(1) This U.S. non-provisional patent application claims priority under 35 U.S.C. § 119 to Korean Patent Application No. 10-2020-0076011, filed on Jun. 22, 2020, in the Korean Intellectual Property Office, the entire contents of which are hereby incorporated by reference.

BACKGROUND OF THE INVENTION

(2) The present disclosure relates to a semiconductor package.

(3) A semiconductor package is configured to allow a semiconductor chip to be easily used as a part of an electronic product. Conventionally, the semiconductor package includes a printed circuit board (PCB) and a semiconductor chip, which is mounted on the PCB and is electrically connected to the PCB using bonding wires or bumps. With development of the electronics industry, many studies are being conducted to improve reliability of the semiconductor package and to reduce a size of the semiconductor package.

SUMMARY

(4) An embodiment of the inventive concept provides a semiconductor package with improved reliability.

(5) According to an embodiment of the inventive concept, a semiconductor package may include a first redistribution substrate, a first semiconductor chip on the first redistribution substrate, and a connection terminal between the first redistribution substrate and the first semiconductor chip. The first redistribution substrate may include a first insulating layer, a plurality of first redistribution patterns, which are vertically stacked in the first insulating layer, and each of which includes a plurality of interconnection portions and a plurality of via portions, and a first bonding pad on a first interconnection portion of a topmost one of the first redistribution patterns. The topmost first redistribution pattern may include a first metallic material and the first bonding pad may include a second metallic material that is different from the first metallic material. The first bonding pad may have a first surface and a second surface, which are opposite to each other. The first surface of the first bonding pad may be in contact with a top surface of the first interconnection portion of the topmost first redistribution pattern. A center portion of the second surface of the first bonding pad may be in contact with the connection terminal. The first insulating layer may be extended to be in contact with an edge portion of the second surface of the first bonding pad.

(6) According to an embodiment of the inventive concept, a semiconductor package may include a first redistribution substrate having a first surface and a second surface, which are opposite to each other, a first semiconductor chip disposed on the first surface of the first redistribution substrate to have chip pads facing the first surface of the first redistribution substrate, and outer coupling terminals on the second surface of the first redistribution substrate. The first redistribution substrate may include a first insulating layer, a plurality of first redistribution patterns, which are vertically stacked in the first insulating layer, and each of which includes a plurality of interconnection portions and a plurality of via portions, and an under-bump pattern between the outer coupling terminals and a first interconnection portion of one of the first redistribution patterns, which is adjacent to the second surface of the first redistribution substrate. A first via portion of an uppermost redistribution pattern, which is adjacent to the first surface of the first redistribution substrate, may be in contact with one of the chip pads. The under-bump pattern may have a first surface and a second surface, which are opposite to each other. The first surface of the under-bump pattern may be in contact with a bottom surface of a lowermost interconnection portion of one of the first redistribution patterns, which is adjacent to the second surface of the first redistribution substrate. The first insulating layer may be extended to cover an edge portion of the second surface of the under-bump pattern.

(7) According to an embodiment of the inventive concept, a semiconductor package may include a first semiconductor package and a second semiconductor package on the first semiconductor package. The first semiconductor package may include a first redistribution substrate, a first semiconductor chip on the first redistribution substrate, a second redistribution substrate, which is spaced apart from the first redistribution substrate, with the first semiconductor chip interposed therebetween, a connection terminal between the first redistribution substrate and the first semiconductor chip, and a conductive pillar between the first redistribution substrate and the second redistribution substrate. The first redistribution substrate may include a first redistribution pattern and a second redistribution pattern, which are vertically stacked and each of which includes a plurality of via portions and a plurality of interconnection portions, a first bonding pad in contact with a top surface of a first interconnection portion of the second redistribution pattern, and an insulating layer covering the first and second redistribution patterns and a portion of a top surface of the first bonding pad. The insulating layer may be absent between the first bonding pad and the second redistribution pattern.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

- (1) Example embodiments will be more clearly understood from the following brief description taken in conjunction with the accompanying drawings. The accompanying drawings represent non-limiting, example embodiments as described herein.
- (2) FIG. 1 is a sectional view illustrating a semiconductor package according to an embodiment of the inventive concept.
- (3) FIG. 2A is an enlarged sectional view of a portion 'aa' of FIG. 1.
- (4) FIG. 2B is a plan view schematically illustrating a planar shape of the portion 'aa' of FIG. 1.
- (5) FIGS. 3A to 3J are sectional views illustrating a process of fabricating a semiconductor package, according to an embodiment of the inventive concept.
- (6) FIG. 4 is a sectional view illustrating a semiconductor package according to an embodiment of the inventive concept.
- (7) FIG. 5 is an enlarged sectional view of a portion 'bb' of FIG. 4.
- (8) FIG. 6 is a plan view illustrating a semiconductor package according to an embodiment of the inventive concept.
- (9) FIG. 7 is a sectional view taken along a line I-I' of FIG. 6.

DETAILED DESCRIPTION

- (10) Example embodiments of the inventive concepts will now be described more fully with reference to the accompanying drawings, in which example embodiments are shown.
- (11) FIG. 1 is a sectional view illustrating a semiconductor package according to an embodiment of the inventive concept.
- (12) Referring to FIG. 1, a semiconductor package 1 may include a first semiconductor package PK1 and a second semiconductor package PK2 on the first semiconductor package PK1. The semiconductor package 1 may have a package-on-package structure. It will be understood that, although the terms first, second, third etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. Unless the context indicates otherwise, these terms are only used to distinguish one element, component, region, layer or section from another element, component, region, layer or section, for example as a naming convention. Thus, a first element, component, region, layer or section discussed below in one section of the specification could be termed a second element, component, region, layer or section in another section of the specification or in the claims without departing from the teachings of the present invention. In addition, in

certain cases, even if a term is not described using “first,” “second,” etc., in the specification, it may still be referred to as “first” or “second” in a claim in order to distinguish different claimed elements from each other.

(13) The first semiconductor package **PK1** may include a lower redistribution substrate **1000**, a first semiconductor chip **700**, an upper redistribution substrate **2000**, a conductive pillar **930**, and a first molding member **950**.

(14) The lower redistribution substrate **1000** may include a first protection layer **20**, a first redistribution layer **100**, a second redistribution layer **200**, and a third redistribution layer **300**, which are sequentially stacked. FIG. 1 illustrates an example, in which the lower redistribution substrate **1000** includes three redistribution layers, but the inventive concept is not limited to this example. For example, one or more redistribution layers may be further provided or may be omitted.

(15) The lower redistribution substrate **1000** may have a first surface **1000a** and a second surface **1000b**, which are opposite to each other. A direction, which is parallel to the first surface **1000a** of the lower redistribution substrate **1000**, may be defined as a first direction **D1**. A direction, which is perpendicular to the first surface **1000a** of the lower redistribution substrate **1000**, may be defined as a second direction **D2**.

(16) A thickness **H1** of the lower redistribution substrate **1000** in the second direction **D2** may range from about 40 μm to 60 μm . Terms such as “about” or “approximately” may reflect amounts, sizes, orientations, or layouts that vary only in a small relative manner, and/or in a way that does not significantly alter the operation, functionality, or structure of certain elements. For example, a range from “about 0.1 to about 1” may encompass a range such as a 0%-5% deviation around 0.1 and a 0% to 5% deviation around 1, especially if such deviation maintains the same effect as the listed range.

(17) In the present specification, the lower redistribution substrate **1000** and the upper redistribution substrate **2000** should not be understood as a conventional printed circuit board (PCB). For example, the lower redistribution substrate **1000** and the upper redistribution substrate **2000** may not include a core layer including an epoxy compound impregnated with glass fibers.

(18) Under-bump patterns **10** may be provided in the first protection layer **20**. The first protection layer **20** may include at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers. The under-bump patterns **10** may be formed of or include, for example, copper.

(19) The first redistribution layer **100** may include first redistribution patterns **110** and a first insulating layer **120**. The second redistribution layer **200** may include second redistribution patterns **210** and a second insulating layer **220**. The third redistribution layer **300** may include third redistribution patterns **310** and a third insulating layer **320**.

(20) The first insulating layer **120**, the second insulating layer **220**, and the third insulating layer **320** may include at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers.

(21) In an embodiment, there may be no measurable interface between any of the first protection layer **20** and the first to third insulating layers **120**, **220**, and **320**. That is, the first protection layer **20** and the first to third insulating layers **120**, **220**, and **320** may be considered as a single insulating layer.

(22) Each of the first to third redistribution patterns **110**, **210**, and **310** may include seed/barrier patterns **11** and conductive patterns **21**. The seed/barrier patterns **11** may be formed of or include at least one of copper or titanium. The conductive patterns **21** may be formed of or include copper.

(23) There may be a measurable interface between each seed/barrier pattern **11** and a respective conductive pattern **21**. The seed/barrier pattern **11** may be locally provided on a bottom surface of the conductive pattern **21**. The seed/barrier pattern **11** may not be provided on a side surface of the conductive pattern **21**. Thus, a bottom surface of each of the conductive patterns **21** may be in

contact with a respective seed/barrier pattern **11**, and the side surface of each of the conductive patterns **21** may be in contact with the insulating layer **120**, **220**, or **320**. It should be appreciated that use of the singular form of an object/element in this application (e.g., “conductive pattern **21**”) may apply to all of a plurality of like objects/elements (e.g., to all of the plurality of conductive patterns **21**, such as those shown in the figures) unless context dictates otherwise.

(24) Each of the first redistribution patterns **110** may include a first via portion **V1** and a first interconnection portion **L1**, which are directly connected to each other to form a single object. The first via portion **V1** may fill a first via hole **VH1** in the first protection layer **20** and may be in contact with a top surface of the under-bump pattern **10**. The first interconnection portion **L1** may be provided on a top surface of the first protection layer **20** and the first via portion **V1** and may be directly connected to the first via portion **V1**. It will be understood that when an element is referred to as being “connected” or “coupled” to or “on” another element, it can be directly connected or coupled to or on the other element or intervening elements may be present. In contrast, when an element is referred to as being “directly connected” or “directly coupled” to another element, or as “contacting” or “in contact with” another element, there are no intervening elements present at the point of contact.

(25) Each of the second redistribution patterns **210** may include a second via portion **V2** and a second interconnection portion **L2**, which are directly connected to each other to form a single object. The second via portion **V2** may fill a second via hole **VH2** in the first insulating layer **120** and may be in contact with a top surface of the first interconnection portion **L1** of the first redistribution pattern **110**. The second interconnection portion **L2** may be provided on a top surface of the first insulating layer **120** and the second via portion **V2** and may be directly connected to the second via portion **V2**.

(26) Each of the third redistribution patterns **310** may include a third via portion **V3** and a third interconnection portion **L3**, which are directly connected to each other to form a single object. The third via portion **V3** may fill a third via hole **VH3** in the second insulating layer **220** and may be in contact with a top surface of the second interconnection portion **L2** of the second redistribution pattern **210**. The third interconnection portion **L3** may be provided on a top surface of the second insulating layer **220** and the third via portion **V3** and may be directly connected to the third via portion **V3**.

(27) In the present specification, the via portions constituting the redistribution patterns may be locally provided between the interconnection portions that are vertically adjacent to each other. Thus, according to an embodiment of the inventive concept, each of the individual vias do not penetrate a plurality of the insulating layers **120**, **220**, or **320**.

(28) The third redistribution patterns **310** may be the topmost redistribution patterns of the redistribution patterns **110**, **210**, and **310**. For example, the third redistribution patterns **310** may be the redistribution patterns, of the redistribution patterns **110**, **210**, and **310**, that are disposed closest to the first surface **1000a** of the lower redistribution substrate **1000**.

(29) The first redistribution patterns **110** may be the bottommost redistribution patterns of the redistribution patterns **110**, **210**, and **310**. For example, the first redistribution patterns **110** may be redistribution patterns that are disposed closest to the second surface **1000b** of the lower redistribution substrate **1000**.

(30) FIG. 2A is an enlarged sectional view of a portion ‘aa’ of FIG. 1. Referring to FIG. 2A, a first bonding pad **610** may be provided on the third interconnection portion **L3** of the third redistribution pattern **310**.

(31) The first bonding pad **610** may include a first surface **SF1** and a second surface **SF2**, which are opposite to each other. The first surface **SF1** of the first bonding pad **610** may be in contact with a top surface of the third interconnection portion **L3**. A portion of the second surface **SF2** of the first bonding pad **610** may be in contact with a connection terminal **708**, which will be described below. The remaining portion of the second surface **SF2** of the first bonding pad **610** may be in contact

with the third insulating layer **320**. In detail, a center portion of the second surface SF2 of the first bonding pad **610** may be in contact with the connection terminal **708**, and an edge portion of the second surface SF2 of the first bonding pad **610** and a side surface of the first bonding pad **610** may be in contact with the third insulating layer **320**.

(32) The first bonding pad **610** may include a first metal pattern **611** and a second metal pattern **612**. The third interconnection portion L3 and the first metal pattern **611** of the first bonding pad **610** may be in contact with each other, without any via interposed therebetween.

(33) Each of the first and second metal patterns **611** and **612** may be formed of or include a metallic material, which is different from the material (e.g., copper) of the conductive pattern **21**. The first metal patterns **611** may be formed of or include a first metallic material. The second metal patterns **612** may be formed of or include a second metallic material. The first metallic material and the second metallic material may be different. In an embodiment, the first metal pattern **611** may be formed of or include nickel (Ni), and the second metal pattern **612** may be formed of or include gold (Au). The first metal pattern **611** may be used as a barrier layer preventing a material (e.g., copper) in the conductive pattern **21** of the third redistribution pattern **310** from being diffused. Since the second metal pattern **612** is formed of or includes gold, it may be used as a wetting layer.

(34) In an embodiment, since the first bonding pad **610** is in contact with the third interconnection portion L3 of the third redistribution pattern **310** without any via interposed therebetween, it may be possible to reduce a length of an electrical path from the first semiconductor chip **700** to an outer coupling terminal **908**, in the structure of FIG. 1.

(35) In the third redistribution pattern **310**, the top surface LV1 of the third interconnection portion L3 may be partially recessed at a region overlapped with the third via portion V3. The lowermost portion of the partially recessed region of the top surface LV1 of the third interconnection portion L3, which is vertically overlapped with the third via portion V3, may be positioned at a lower level than the other portion of the top surface LV1 of the third interconnection portion L3 or the first surface SF1 of the first bonding pad **610**. In the first and second redistribution patterns **110** and **210**, the interconnection portions L1 and L2, which are vertically overlapped with the via portions V1 and V2, may also have partially-recessed top surfaces.

(36) A sum T1 of thicknesses of the third via portion V3 and the third interconnection portion L3, which are vertically overlapped with each other, may be larger than a thickness T2 of the first bonding pad **610**.

(37) The third insulating layer **320** may be provided to cover edge portions of the top surfaces of the third interconnection portion L3 and edge portions of the first bonding pad **610**. A portion of the third insulating layer **320** overlapped with the first bonding pad **610** may protrude upward relative to the other portion of the third insulating layer **320**.

(38) In the present specification, a solder mask material (e.g., an epoxy material used for a conventional PCB substrate) may be absent in the third insulating layer **320**. In the case of the conventional PCB substrate, a solder mask material may be used to cover the entire portion of the interconnection structure, other than a pad portion. Also, a prepreg material, in which an epoxy compound impregnated with glass fibers is included, may be used as an insulating layer covering an inner interconnection layer. This means that the solder mask material covering the entire portion of the interconnection structure other than the pad portion is different from the prepreg material covering the inner interconnection layer. By contrast, according to an embodiment of the inventive concept, the third insulating layer **320** may be formed of or include substantially the same material as the first insulating layer **120** and the second insulating layer **220**.

(39) FIG. 2B is a plan view schematically illustrating the top surface of the third interconnection portion L3 of the third redistribution pattern **310**, the first bonding pad **610**, and the third insulating layer **320**.

(40) Referring to FIG. 2B, the third interconnection portion L3 of the third redistribution pattern **310** may include a first portion L31 and a second portion L32. The first portion L31 may be wider

than the second portion **L32** and may be vertically overlapped with the first bonding pad **610**. The first portion **L31** may have a first width **W1** in the first direction **D1**. The first bonding pad **610** may have a second width **W2** in the first direction **D1**. The second width **W2** may be smaller than the first width **W1**.

(41) A third width **W3** of the top surface of the first bonding pad **610** exposed through the third insulating layer **320** may be greater than half of the second width **W2**. For example, an area of the exposed top surface of the first bonding pad **610** may be greater than area of the top surface of the first bonding pad **610** covered with the third insulating layer **320**.

(42) Referring back to FIGS. **1** and **2A**, the first semiconductor chip **700** may be provided on the lower redistribution substrate **1000**. The first semiconductor chip **700** may be, for example, a logic chip. The first semiconductor chip **700** may be disposed on the lower redistribution substrate **1000** such that a first chip pad **705** of the first semiconductor chip **700** faces the lower redistribution substrate **1000**.

(43) The connection terminal **708** may be in contact with both of the first bonding pad **610** and the first chip pad **705** and may electrically connect the first chip pad **705** and the first bonding pad **610**. The first semiconductor chip **700** may be electrically connected to the lower redistribution substrate **1000** through the connection terminal **708**. The connection terminal **708** may include at least one of solder, pillar, and bump. The connection terminal **708** may be formed of or include at least one of conductive materials (e.g., tin (Sn) and silver (Ag)).

(44) The top surface of the first bonding pad **610** exposed through the third insulating layer **320** may be in contact with the connection terminal **708**. An under-fill pattern **710** may be provided in a gap region between the third insulating layer **320** and the first semiconductor chip **700**. The under-fill pattern **710** may be spaced apart from the first bonding pad **610**, with the third insulating layer **320** interposed therebetween. In other words, the first bonding pad **610** may not be in contact with the under-fill pattern **710**.

(45) A conductive pillar **930** may be provided on the lower redistribution substrate **1000** and in the first molding member **950**. The conductive pillar **930** may be laterally spaced apart from the first semiconductor chip **700**. The conductive pillar **930** may be in contact with the top surface of the third interconnection portion **L3** of at least one of the third redistribution patterns **310**. The conductive pillar **930** may include a via portion that is in contact with the top surface of the third interconnection portion **L3**.

(46) The conductive pillar **930** may be electrically connected to the outer coupling terminal **908** or the first semiconductor chip **700** through the redistribution patterns **110**, **120**, and **130**. The conductive pillar **930** may be formed of or include, for example, copper. A height of the conductive pillar **930** from the top surface of the third insulating layer **320** may be, for example, about 200 μm .

(47) The first molding member **950** may be formed on the lower redistribution substrate **1000** to cover the lower redistribution substrate **1000**. The first molding member **950** may cover the top surface of the third insulating layer **320** and a side surface of the under-fill pattern **710**. The first molding member **950** may cover a side surface of the conductive pillar **930**, but not the top surface of the conductive pillar **930**. The first molding member **950** may also cover top and side surfaces of the first semiconductor chip **700**.

(48) The outer coupling terminals **908** may be disposed on the second surface **1000b** of the lower redistribution substrate **1000** and the first protection layer **20**. Each of the outer coupling terminals **908** may be vertically overlapped with a respective under-bump pattern **10**. Additionally, each of the outer coupling terminals **908** may be in contact with the respective under-bump pattern **10**. The outer coupling terminal **908** may be coupled to the first chip pad **705** through the under-bump pattern **10** and the redistribution patterns **110**, **210**, and **310**. Thus, it may be unnecessary to align the outer coupling terminal **908** to the first chip pad **705** in a vertical direction. In an embodiment, a plurality of the outer coupling terminals **908** may be provided, and in this case, at least one of the outer coupling terminal **908** may not be vertically overlapped with the first semiconductor chip

700. This may make it possible to increase a degree of freedom in the arrangement of the outer coupling terminal **908**. The semiconductor package **1** may be a fan-out semiconductor package fabricated by a chip-last process.

(49) The upper redistribution substrate **2000** may be disposed on a top surface of the first molding member **950** and a top surface of the conductive pillar **930**.

(50) The upper redistribution substrate **2000** may include a second protection layer **30**, a fourth redistribution layer **400**, and a fifth redistribution layer **500**. The upper redistribution substrate **2000** is illustrated to include two redistribution layers **400** and **500**, but the inventive concept is not limited to this example. For example, the upper redistribution substrate **2000** may further include at least one additional redistribution layer, or one of the redistribution layers may be omitted.

(51) A thickness **H2** of the upper redistribution substrate **2000** may range from about 10 to 60 μm .

(52) The fourth redistribution layer **400** may be substantially the same as the first redistribution layer **100** or the second redistribution layer **200** described above. The fifth redistribution layer **500** may be substantially the same as the third redistribution layer **300** described above.

(53) The fourth redistribution layer **400** may include fourth redistribution patterns **410** and a fourth insulating layer **420**. The fifth redistribution layer **500** may include fifth redistribution patterns **510** and a fifth insulating layer **520**. The fifth redistribution layer **500** may be the topmost layer of the redistribution layers. For example, the fifth redistribution layer **500** may be the redistribution layer, of the redistribution layers **400** and **500**, that is disposed farthest from the first surface **1000a** of the lower redistribution substrate **1000**.

(54) Each of the fourth redistribution patterns **410** may include a fourth via portion **V4** and a fourth interconnection portion **L4**, which are connected to each other to form a single object. The fourth via portion **V4** may fill a fourth via hole **VH4** in the second protection layer **30** and may be in contact with the top surface of the conductive pillar **930**. The fourth interconnection portion **L4** may be provided on a top surface of the second protection layer and the fourth via portion **V4** and may be connected to the fourth via portion **V4**.

(55) Each of the fifth redistribution patterns **510** may include a fifth via portion **V5** and a fifth interconnection portion **L5**, which are connected to each other to form a single object. The fifth via portion **V5** may fill a fifth via hole **VH5** in the fourth insulating layer **420** and may be in contact with a top surface of the fourth interconnection portion **L4** of the fourth redistribution pattern **410**. The fifth interconnection portion **L5** may be provided on a top surface of the fourth insulating layer **420** and the fifth via portion **V5** and may be connected to the fifth via portion **V5**.

(56) The second protection layer **30**, and the fourth and fifth insulating layers **420**, and **520** may include at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers. In an embodiment, there may be no measurable interface between the second protection layer **30** and the fourth insulating layer **420** and between the fourth insulating layer **420** and the fifth insulating layer **520**. In other words, the second protection layer **30**, the fourth insulating layer **420**, and the fifth insulating layer **520** may be inspected as a single insulating layer.

(57) A second bonding pad **620** may be provided on the fifth interconnection portion **L5** of the fifth redistribution pattern **510**. In an embodiment, the shape of the topmost surface of the upper redistribution substrate **2000** may be substantially the same or similar to that of the lower redistribution substrate **1000**.

(58) The fifth redistribution pattern **510**, the fifth insulating layer **520**, and the second bonding pad **620** may correspond to the third redistribution pattern **310**, the third insulating layer **320**, and the first bonding pad **610**, respectively. The shape of each of the fifth redistribution pattern **510**, the fifth insulating layer **520**, and the second bonding pad **620** may be substantially the same as or similar to that of a corresponding one of the third redistribution pattern **310**, the third insulating layer **320**, and the first bonding pad **610**, respectively, as described with reference to FIGS. 2A and 2B.

(59) The second bonding pad **620** may include a third metal pattern **621** and a fourth metal pattern **622**. The third metal pattern **621** may be formed of or include nickel (Ni), and the fourth metal pattern **622** may be formed of or include gold (Au). The third metal pattern **621** may be in contact with the fifth interconnection portion L5 of the fifth redistribution pattern **510**, without any via interposed therebetween. The fourth metal pattern **622** may be in contact with a package coupling terminal **808**, which will be described below. The fifth insulating layer **520** may be provided to cover an edge portion of a top surface of the second bonding pad **620** and to not cover a center portion of the second bonding pad **620**.

(60) The second semiconductor package PK2 may be provided on the upper redistribution substrate **2000**. The second semiconductor package PK2 may include a package substrate **810**, a second semiconductor chip **800**, and a second molding member **850**. The package substrate **810** may be a printed circuit board or a redistribution substrate. Metal pads **815** and **817** may be provided on opposite surfaces of the package substrate **810**.

(61) In an embodiment, the second semiconductor chip **800** may be a memory chip, such as a DRAM chip or a NAND FLASH memory chip. The second semiconductor chip **800** may be of a different kind from that of the first semiconductor chip **700**. A second chip pad **805** may be provided on a surface of the second semiconductor chip **800** and may be connected to the metal pad **815** of the package substrate **810** in a wire bonding manner.

(62) The package coupling terminal **808** may be disposed between the first semiconductor package PK1 and the second semiconductor package PK2. The package coupling terminal **808** may be in contact with the second bonding pad **620** and the metal pad **817**. A lower portion of the package coupling terminal **808** may be enclosed by a protruding portion of the fifth insulating layer **520**.

(63) The package coupling terminal **808** may be electrically connected to the second bonding pad **620** and the metal pad **817**. Thus, the second semiconductor package PK2 may be electrically connected to the first semiconductor chip **700** and the outer coupling terminal **908** through the upper redistribution substrate **2000**, the package coupling terminal **808**, and the conductive pillar **930**.

(64) FIGS. 3A to 3J are sectional views illustrating a process of fabricating a semiconductor package, according to an embodiment of the inventive concept. For concise description, an element previously described with reference to FIG. 1 may be identified by the same reference number without repeating an overlapping description thereof.

(65) Referring to FIG. 3A, a carrier substrate **900** covered with an adhesive layer **910** may be provided. A first seed layer **11a** may be formed on the carrier substrate **900** to cover a top surface of the adhesive layer **910**. The first seed layer **11a** may be formed by a deposition process. The adhesive layer **910** may attach the first seed layer **11a** to the carrier substrate **900**.

(66) A first photomask pattern PM1 may be formed on a top surface of the first seed layer **11a**. The first photomask pattern PM1 may include an opening, which defines a space for the under-bump pattern **10**. The first photomask pattern PM1 may be formed by forming, exposing, and developing a photoresist layer. The first photomask pattern PM1 may be formed to expose the first seed layer **11a**. The under-bump pattern **10** may be formed in the opening by an electroplating process, in which the first seed layer **11a** is used as an electrode.

(67) Referring to FIG. 3B, the first photomask pattern PM1 may be removed. Thereafter, the first protection layer **20** may be formed to cover the under-bump pattern **10**. The first protection layer **20** may be formed by a coating process (e.g., a spin coating process or a slit coating process). The first protection layer **20** may be patterned by an exposure and developing process to have the first via hole VH1 defining the via portion V1 of the first redistribution pattern **110**. The first via hole VH1 may expose the top surface of the under-bump pattern **10**. A curing process may be performed on the first protection layer **20**. A second seed/barrier layer **11b** may be formed to cover the top surface of the first protection layer **20**. A second photomask pattern PM2 may be formed on the second seed/barrier layer **11b**. The second photomask pattern PM2 may define a region, in which the first

interconnection portion **L1** of the first redistribution pattern **110** will be formed by a subsequent process. Thereafter, the first conductive pattern **21a** may be formed on the second seed/barrier layer **11b** by an electroplating method.

(68) Referring to FIG. 3C, the second photomask pattern **PM2** may be removed. Thereafter, the second seed/barrier layer **11b** may be etched to form the seed/barrier pattern **11**. As a result, the first redistribution pattern **110** including the first conductive pattern **21a** and the seed/barrier pattern **11** may be formed. The entire portion of the second seed/barrier layer **11b**, except portions vertically overlapped with the first conductive patterns **21a**, may be removed by the etching process. The etching process may be, for example, a wet etching process.

(69) Referring to FIG. 3D, the first insulating layer **120** may be formed to cover the first redistribution pattern **110** and the first protection layer **20**. The first insulating layer **120** may be formed by a coating process (e.g., a spin coating process or a slit coating process). The first insulating layer **120** may be patterned by an exposure and developing process to have the second via hole **VH2** defining the second via portion **V2** of the second redistribution pattern **210** to be described below. The second via hole **VH2** may expose a portion of the top surface of the first interconnection portion **L1** of the first redistribution pattern **110**. A curing process may be performed on the first insulating layer **120**. As a result, the first redistribution layer **100** including the first redistribution pattern **110** and the first insulating layer **120** may be formed.

(70) Thereafter, the second redistribution pattern **210** may be formed. The second redistribution pattern **210** may be formed by substantially the same method as that for the first redistribution pattern **110**. The second insulating layer **220** may be formed to cover the second redistribution pattern **210** and may be cured. The second insulating layer **220** may be formed by substantially the same method as that for the first insulating layer **120**. As a result, the second redistribution layer **200** including the second redistribution pattern **210** and the second insulating layer **220** may be formed.

(71) A third seed/barrier layer **11c** and a third conductive pattern **21c** may be formed on the second redistribution layer **200**.

(72) Referring to FIG. 3E, a third photomask pattern **PM3** may be formed on the third conductive pattern **21c** and the third seed/barrier layer **11c**. The third photomask pattern **PM3** may be formed so that a portion of the top surface of the third interconnection portion **L3** of the third redistribution pattern **310** is exposed, as described below. The third photomask pattern **PM3** may include openings defining regions, in which the first bonding pads **610** will be formed.

(73) The first metal pattern **611** and the second metal pattern **612** may be sequentially formed by an electroplating process. The first metal pattern **611** may be formed to be in contact with the top surface of the third interconnection portion **L3** of the third redistribution pattern **310**.

(74) Referring to FIG. 3F, the third photomask pattern **PM3** may be removed. Thereafter, the seed/barrier pattern **11** may be formed by performing an etching process on the third seed/barrier layer **11c**. As a result, the third redistribution pattern **310** including the third conductive pattern **21c** and the seed/barrier pattern **11** may be formed. The entire portion of the third seed/barrier layer **11c**, except portions vertically overlapped with the third conductive patterns **21c**, may be removed by the etching process. The third insulating layer **320** may be formed to cover the third redistribution pattern **310** and the first bonding pad **610**. The third insulating layer **320** may be formed by substantially the same method as that for the first and second insulating layers **120** and **220**.

(75) As a result, the third redistribution layer **300** including the third redistribution pattern **310** and the third insulating layer **320** may be formed. Furthermore, the lower redistribution substrate **1000** including the first protection layer **20** and the first to third redistribution layers **100**, **200**, and **300** may be formed.

(76) Referring to FIG. 3G, a patterning process may be performed to expose a portion of the top surface of the first bonding pad **610** and a portion of the top surface of the interconnection portion **L3** of the third redistribution pattern **310**. The patterning process may include performing an

exposure and developing process on the third insulating layer **320**. As a result of the patterning process, first openings **OP1** may be formed to expose portions of the top surface of the first bonding pad **610**, and second openings **OP2** may be formed to expose portions of the top surface of the third interconnection portion **L3** of the third redistribution pattern **310**. A via portion of the conductive pillar **930** may be formed in the second opening **OP2** by a process to be described below.

(77) According to a conventional process, the third insulating layer **320** may be formed immediately after the formation of the third redistribution pattern **310**, and an exposure and developing may be performed to form a via hole exposing the third interconnection portion **L3** of the third redistribution pattern **310**. Thereafter, a via may be formed on the third insulating layer **320** to fill the via hole, and the bonding pad **610** may be formed on the via.

(78) As previously described with reference to FIG. 2A, the top surface **LV1** of the third interconnection portion **L3** of the third redistribution pattern **310** vertically overlapped with the third via portion **V3** may have a recessed portion, which is positioned at a level lower than the other portion of the top surface of the third interconnection portion **L3**.

(79) According to the conventional process, in the case where a via hole is formed on the third interconnection portion **L3** positioned at a low level, a failure may occur in which the third interconnection portion **L3** is not exposed during the formation of the via hole, due to a relatively large thickness of the third insulating layer **320**. In this case, even when a via is formed in the via hole, the via may not be electrically connected to the third interconnection portion **L3**. Especially, this failure may easily occur during a process of exposing the uppermost insulating layer, in a structure (e.g., a stack via structure), in which vias and interconnection lines are vertically overlapped with each other.

(80) By contrast, according to an embodiment of the inventive concept, the above failure may be reduced, because the first bonding pad **610** is directly formed on the uppermost redistribution pattern **310**.

(81) Referring to FIG. 3H, the conductive pillar **930** may be formed. The formation of the conductive pillar **930** may include forming a photoresist pattern (not shown) to define a gap region, in which the conductive pillar **930** will be formed, filling the gap region with a conductive material, and removing the photoresist pattern.

(82) Next, the first semiconductor chip **700** may be disposed on the lower redistribution substrate **1000** such that the first chip pad **705** of the first semiconductor chip **700** faces the lower redistribution substrate **1000**. The disposing of the first semiconductor chip **700** on the lower redistribution substrate **1000** may be performed by a thermo-compression process.

(83) The connection terminal **708** may be attached to the top surface of the first bonding pad **610**, which is exposed through the first opening **OP1** of the third insulating layer **320**. Since the third insulating layer **320** has a dam-shaped top surface surrounding the first bonding pad **610**, the third insulating layer **320** may prevent a conductive material, which is supplied to form the connection terminal **708**, from flowing toward other connection terminals **708** during a thermocompression process. In addition, due to the afore-described structure of the third insulating layer **320**, the first bonding pad **610** and the connection terminal **708** may be in good contact with each other in a self-aligned manner or without a misalignment issue. Since the third insulating layer **320** serves as the dam or the overflow-preventing structure, the connection terminal **708** may be in contact with the entire region of the top surface of the first bonding pad **610** that is exposed through the third insulating layer **320**.

(84) The under-fill pattern **710** may be formed to fill an empty region between the first semiconductor chip **700** and the lower redistribution substrate **1000**.

(85) The under-fill pattern **710** may be provided to prevent stress and deformation issues, which are caused by a difference in thermal expansion coefficient between the lower redistribution substrate **1000** and the first semiconductor chip **700**. In a conventional process, the first bonding pad **610**

may be exposed to the outside, on the top surface of the third insulating layer **320**, and thus, the side surface of the first bonding pad **610** may be in contact with the under-fill pattern **710**. In this case, a stress may be produced by a difference in thermal expansion coefficient between the first bonding pad **610** and the under-fill pattern **710** and may be exerted on the third insulating layer **320** adjacent thereto. Since the third insulating layer **320** has a relatively low strength, a crack may be easily formed in the third insulating layer **320**. Furthermore, there may be a crack-propagation issue, in which the crack is propagated from the third insulating layer **320** toward the first protection layer **20**.

(86) According to an embodiment of the inventive concept, since a portion of the first bonding pad **610** is enclosed by the third insulating layer **320** and the other portion is in contact with the connection terminal **708**, the first bonding pad **610** may be spaced apart from the under-fill pattern **710**. Accordingly, the first bonding pad **610** does not contact the under-fill pattern **710**. Thus, it is possible to reduce a crack issue, which may occur when the under-fill pattern **710** is in contact with the first bonding pad **610**.

(87) Referring to FIG. 3I, a first molding member **950** may be formed to cover the top surface of the lower redistribution substrate **1000**, the first semiconductor chip **700**, and the conductive pillar **930**. The upper redistribution substrate **2000** may be formed on the first molding member **950**.

(88) The formation of the upper redistribution substrate **2000** may include forming the fourth redistribution layer **400**, forming the fifth redistribution layer **500**, and forming the second bonding pad **620**. The fourth redistribution layer **400** may be formed by substantially the same method as that for the first or second redistribution layer **100** or **200** described above. The fifth redistribution layer **500** may be formed by substantially the same method as that for the third redistribution layer **300** described above. The second bonding pad **620** may be formed by substantially the same method as that for the first bonding pad **610** described above.

(89) A singulation process may be performed along a dash-dot line which is drawn from the upper redistribution substrate **2000** to the lower redistribution substrate **1000**. Thereafter, the carrier substrate **900**, the adhesive layer **910**, and the first seed layer **11a** may be removed. The removal of the first seed layer **11a** may be achieved by an etching process. As a result of the removal of the first seed layer **11a**, the under-bump patterns **10** may be exposed to the outside.

(90) Referring to FIG. 3J, the first semiconductor package PK1 may be manufactured by forming the outer coupling terminals **908** on the exposed under-bump patterns **10**. Referring back to FIG. 1, the second semiconductor package PK2 may be mounted on the first semiconductor package PK1.

(91) FIG. 4 is a sectional view illustrating a semiconductor package 2 according to an embodiment of the inventive concept. FIG. 5 is an enlarged sectional view of a portion 'bb' of FIG. 4. For concise description, an element previously described with reference to FIG. 1 may be identified by the same reference number without repeating an overlapping description thereof. The semiconductor package 2 may be a fan-out semiconductor package fabricated by a chip-first process.

(92) Referring to FIG. 4, the first semiconductor chip **700** and the lower redistribution substrate **1000** may be electrically connected to each other, without the connection terminal **708** of FIG. 1. The lower redistribution substrate **1000** may include a first protection layer **20**, a first redistribution layer **100**, a second redistribution layer **200**, and a third redistribution layer **300**, which are sequentially stacked on a surface **700b** of the first semiconductor chip **700**.

(93) The first redistribution patterns **110** may be the topmost redistribution patterns of the redistribution patterns **110**, **210**, and **310**. The first redistribution patterns **110** may be a redistribution pattern that is disposed closest to the first surface **1000a** of the lower redistribution substrate **1000**.

(94) The third redistribution patterns **310** may be the bottommost redistribution patterns of the redistribution patterns **110**, **210**, and **310**. The third redistribution patterns **310** may be redistribution patterns that are disposed closest to the second surface **1000b** of the lower

redistribution substrate **1000**.

(95) The first protection layer **20** may include first via holes **VH1** exposing the first chip pad **705** and a pad portion below the conductive pillar **930**. The first redistribution patterns **110** may be provided on the first protection layer **20** to fill the first via holes **VH1**. Some of the first via portions **V1** of the first redistribution patterns **110** may be in contact with the first chip pads **705**, and the others may be in contact with the pad portion below the conductive pillar **930**. Spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper” and the like, may be used herein for ease of description to describe positional relationships, such as illustrated in the figures, e.g. It will be understood that the spatially relative terms encompass different orientations of the device in addition to the orientation depicted in the figures.

(96) The under-bump patterns **10** may be provided on the third interconnection portions **L3** of some of the third redistribution patterns **310**.

(97) Referring to FIG. 5, the under-bump pattern **10** may have a first surface **SP1** and a second surface **SP2**, which are opposite to each other. The first surface **SP1** of the under-bump pattern **10** and a top surface of the third interconnection portion **L3** may be in contact with each other, without any via interposed therebetween. A thickness **T3** of the under-bump pattern **10** may be larger than the largest thickness **T4** of the third interconnection portion **L3**. The under-bump pattern **10** may be formed of or include copper (Cu), and any seed/barrier pattern may not be interposed between the first surface **SP1** of the under-bump pattern **10** and the top surface of the third interconnection portion **L3**. The conductive pattern **21** may be formed of or include copper. In an embodiment, there may be no measurable interface between the under-bump pattern **10** and the third interconnection portion **L3**.

(98) In an embodiment, since the under-bump pattern **10** is in contact with the third interconnection portion **L3** of the third redistribution pattern **310**, without any via interposed therebetween, it may be possible to reduce a length of an electrical path from the first semiconductor chip **700** to the outer coupling terminal **908**.

(99) A first lower under-bump pattern **631** and a second lower under-bump pattern **632** may be sequentially provided on the second surface **SP2** of the under-bump pattern **10**. The first and second lower under-bump patterns **631** and **632** may be formed of or include a material different from that of the under-bump pattern **10**. The first lower under-bump pattern **631** may be formed of or include nickel and may be used as a barrier layer preventing diffusion of a material (e.g., copper) in the under-bump pattern **10**. The second lower under-bump pattern **632** may be formed of or include gold and may be used as a wetting layer. Side surfaces of the first and second lower under-bump patterns **631** and **632** may be enclosed by the third insulating layer **320**.

(100) The third insulating layer **320** may be provided to cover an edge portion of a top surface of the second lower under-bump pattern **632** and to not cover a center portion of the top surface of the second lower under-bump pattern **632**. A portion of the third insulating layer **320** overlapped with the under-bump pattern **10** may protrude relative to other portions of the third insulating layer **320**. The outer coupling terminal **908** may be in contact with a top surface of the second lower under-bump pattern **632** that is not covered with the third insulating layer **320**.

(101) In an embodiment, the first and second lower under-bump patterns **631** and **632** may be omitted. In this case, the third insulating layer **320** may be provided to cover an edge portion of the second surface **SP2** of the under-bump pattern **10** and to not cover a center portion of the second surface **SP2** of the under-bump pattern **10**. The outer coupling terminal **908** may be in contact with the exposed second surface **SP2** of the under-bump pattern **10**.

(102) The second semiconductor package **PK2** may be configured to have substantially the same structure as the second semiconductor package **PK2** described with reference to FIG. 1. The second bonding pad **620**, the fifth insulating layer **520**, the fifth redistribution pattern **510**, and the package coupling terminal **808** may also be configured to have substantially the same structure as those described with reference to FIG. 1.

(103) FIG. 6 is a plan view illustrating a semiconductor package 3 according to an embodiment of the inventive concept. FIG. 7 is a sectional view taken along a line I-I' of FIG. 6. In order to reduce complexity in the drawings and to provide better understanding of this embodiment, some elements of the semiconductor package 3 may be omitted from FIG. 6. For concise description, an element previously described with reference to FIGS. 1 and 4 may be identified by the same reference number without repeating an overlapping description thereof. The semiconductor package 3 may be a fan-out semiconductor package fabricated by a chip-first process.

(104) Referring to FIGS. 6 and 7, a semiconductor package 3 according to an embodiment of the inventive concept may include the first semiconductor package PK1 including a connection substrate 901. The connection substrate 901 may have a hole 990, which is provided to penetrate the same. When viewed in a plan view, the hole 990 may be located at a center portion of the lower redistribution substrate 1000. The first semiconductor chip 700 may be provided in the hole 990. The connection substrate 901 may be provided on the lower redistribution substrate 1000. As an example, the connection substrate 901 may be fabricated by forming the hole 990 in a printed circuit board. The connection substrate 901 may include base layers 905 and a conductive structure 920.

(105) The base layers 905 may be formed of or include an insulating material. For example, the base layers 905 may be formed of or include at least one of carbon-containing materials, ceramics, or polymers. The base layers 905 may be formed of or include an insulating material different from those of the first protection layer 20, the first insulating layer 120, the second insulating layer 220, and the third insulating layer 320 of the lower redistribution substrate 1000.

(106) The hole 990 may be provided to penetrate the base layers 905. The conductive structure 920 may include a first pad 921, a conductive line 923, vias 924, and a second pad 922.

(107) The first pad 921 may be provided on a bottom surface of the connection substrate 901. The conductive line 923 may be interposed between the base layers 905. The vias 924 may be provided to penetrate the base layers 905 and may be coupled to the conductive line 923. The second pad 922 may be disposed on a top surface of the connection substrate 901 and may be coupled to one of the vias 924. The second pad 922 may be electrically connected to the first pad 921 through the vias 924 and the conductive line 923.

(108) The second pad 922 may not be aligned with the first pad 921 in a vertical direction. The number or the arrangement of the second pads 922 may be different from those of the first pads 921. The conductive structure 920 may be formed of or include at least one of metallic materials. For example, the conductive structure 920 may be formed of or include at least one of copper, aluminum, gold, lead, stainless steel, iron, or alloys thereof.

(109) The first molding member 950 may be provided to fill a region between the first semiconductor chip 700 and the connection substrate 901. An upper hole 970 may be provided on the first molding member 950 to expose the second pad 922 of the conductive structure 920.

(110) In an embodiment, a conductive portion 980 may be provided in the upper hole 970 to fill the upper hole 970. In an embodiment, the conductive portion 980 may be formed of or include at least one of metals.

(111) The lower redistribution substrate 1000 may be provided on a surface of the first molding member 950. The lower redistribution substrate 1000 may include the first protection layer 20, and the first protection layer 20 may include the first via holes VH1 exposing the first pad 921 of the conductive structure 920 and the first chip pad 705. The first redistribution pattern 110 may be provided on the first protection layer 20 to fill the first via hole VH1.

(112) The upper redistribution substrate 2000 may be provided on the top surface of the first molding member 950. The upper redistribution substrate 2000 may include the second protection layer 30, and the second protection layer 30 may include the fourth via hole VH4 exposing the conductive portion 980. The fourth redistribution pattern 410 may be provided on the second protection layer 30 to fill the fourth via hole VH4. The fourth redistribution pattern 410 may be in

contact with the conductive portion **980**.

(113) The second semiconductor package **PK2** may be configured to have substantially the same structure as the second semiconductor package **PK2** described with reference to FIG. **1**. The under-bump pattern **10**, the first lower under-bump pattern **631**, and the second lower under-bump pattern **632** may be configured to have substantially the same features as those described with reference to FIGS. **4** and **5**. The second bonding pad **620**, the fifth insulating layer **520**, the fifth redistribution pattern **510**, and the package coupling terminal **808** may also be configured to have substantially the same features as those described with reference to FIG. **1**.

(114) According to an embodiment of the inventive concept, a bonding pad may be in contact with an interconnection portion of an uppermost redistribution pattern without any via interposed therebetween, and thus, it may be possible to reduce a length of an electrical path from a semiconductor chip to an outer coupling terminal.

(115) While example embodiments of the inventive concept have been particularly shown and described, it will be understood by one of ordinary skill in the art that variations in form and detail may be made therein without departing from the spirit and scope of the attached claims.

Claims

1. A semiconductor package, comprising: a first redistribution substrate having a first surface and a second surface, which are opposite to each other; a first semiconductor chip on the first surface of the first redistribution substrate; and an outer coupling terminal on the second surface of the first redistribution substrate, wherein the first redistribution substrate comprises: a first insulating layer; a first redistribution pattern in the first insulating layer, and includes an interconnection portion and a via portion; and an under-bump pattern between the outer coupling terminal and the interconnection portion of the first redistribution pattern, wherein the under-bump pattern has a third surface and a fourth surface, which are opposite to each other, wherein the third surface of the under-bump pattern is in direct physical contact with the interconnection portion of the first redistribution pattern, and wherein the first insulating layer is in direct physical contact with an edge portion of the fourth surface of the under-bump pattern.
2. The semiconductor package of claim 1, wherein the first semiconductor chip comprises a chip pad, and wherein the via portion of the first redistribution pattern is in direct physical contact with the chip pad.
3. The semiconductor package of claim 1, wherein the first insulating layer comprises at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers.
4. The semiconductor package of claim 1, wherein no via is interposed between the under-bump pattern and the interconnection portion of the first redistribution pattern.
5. The semiconductor package of claim 1, wherein the first insulating layer is absent between the under-bump pattern and the first redistribution pattern.
6. The semiconductor package of claim 1, further comprising a second redistribution substrate, which is vertically spaced apart from the first redistribution substrate with the first semiconductor chip interposed therebetween, wherein the second redistribution substrate comprises: a second insulating layer; a second redistribution pattern in the second insulating layer, and includes an interconnection portion and a via portion; and a bonding pad on the interconnection portion of a topmost one of the second redistribution patterns, wherein the topmost second redistribution pattern comprises a first metallic material and the bonding pad comprises a second metallic material different from the first metallic material, the bonding pad has a fifth surface and a sixth surface, which are opposite to each other, the fifth surface of the bonding pad is in direct physical contact with a top surface of the interconnection portion of the second redistribution pattern, and the second insulating layer is extended to cover an edge portion of the sixth surface of the bonding pad.

and not cover a center portion of the bonding pad.

7. The semiconductor package of claim 6, wherein the second insulating layer is absent between the bonding pad and the second redistribution pattern.

8. The semiconductor package of claim 1, further comprising a second redistribution substrate, which is vertically spaced apart from the first redistribution substrate with the first semiconductor chip interposed therebetween, and a conductive pillar between the first redistribution substrate and the second redistribution substrate.

9. The semiconductor package of claim 1, further comprising a second redistribution substrate, which is vertically spaced apart from the first redistribution substrate with the first semiconductor chip interposed therebetween, a connection substrate having a hole between the first redistribution substrate and the second redistribution substrate, and a first molding structure that fills a region between the first semiconductor chip, and the connection substrate and between the first redistribution substrate and the second redistribution substrate.

10. A semiconductor package, comprising: a first redistribution substrate having a first surface and a second surface, which are opposite to each other; a first semiconductor chip disposed on the first surface of the first redistribution substrate to have chip pads facing the first surface of the first redistribution substrate; and outer coupling terminals on the second surface of the first redistribution substrate, wherein the first redistribution substrate comprises: a first insulating layer; a plurality of first redistribution patterns, which are vertically stacked in the first insulating layer, and each of which includes a plurality of interconnection portions and a plurality of via portions; and an under-bump pattern between a first outer coupling terminal and a first interconnection portion of one of the first redistribution patterns, which is adjacent to the second surface of the first redistribution substrate, wherein a first via portion of an uppermost first redistribution pattern, which is adjacent to the first surface of the first redistribution substrate, is in contact with one of the chip pads, the under-bump pattern has a third surface and a fourth surface, which are opposite to each other, the third surface of the under-bump pattern is in contact with a bottom surface of a lowermost interconnection portion of one of the first redistribution patterns, which is adjacent to the second surface of the first redistribution substrate, and the first insulating layer is extended to cover an edge portion of the fourth surface of the under-bump pattern.

11. The semiconductor package of claim 10, wherein a thickness of the under-bump pattern, in a direction perpendicular to the fourth surface of the under-bump pattern, is thicker than a thickness of the first interconnection portion of the lowermost first redistribution pattern.

12. The semiconductor package of claim 10, wherein a thickness of the first redistribution substrate, measured from the fourth surface of the under-bump pattern, ranges from 40 μm to 60 μm , and the first insulating layer comprises at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers.

13. The semiconductor package of claim 10, wherein the bottom surface of the first insulating layer is positioned at a lower level compared to the fourth surface of the under-bump pattern.

14. The semiconductor package of claim 10, further comprising a bonding pad between the under-bump pattern and the first outer coupling terminal, wherein the bonding pad comprises: a first metal pattern in contact with the fourth surface of the under-bump pattern; and a second metal pattern in contact with the first outer coupling terminal, wherein the under-bump pattern comprises a first metallic material, the first metal pattern comprises a second metallic material, and the second metal pattern comprises a third metallic material, the first, second and third metallic materials each being different from each other.

15. The semiconductor package of claim 14, a level of a lowermost surface of the first insulating layer is lower than a level of a lowermost surface of the second metal pattern.

16. The semiconductor package of claim 14, wherein the first interconnection portion and a second via portion of one of the lowermost first redistribution pattern, are connected to each other to form a single object, and a level of a top surface of the first interconnection portion, which is vertically

overlapped with the second via portion, is higher than a level of a top surface of the first interconnection portion, which is vertically overlapped with the bonding pad.

17. A semiconductor package, comprising: a first redistribution substrate having a first surface and a second surface, which are opposite to each other; a first semiconductor chip on the first surface of the first redistribution substrate; and an outer coupling terminal on the second surface of the first redistribution substrate, wherein the first redistribution substrate comprises: a first insulating layer; and a first redistribution pattern in the first insulating layer, and includes an interconnection portion and a via portion; and an under-bump pattern between the outer coupling terminal and the interconnection portion of the first redistribution pattern, wherein the under-bump pattern has a third surface and a fourth surface, which are opposite to each other, wherein the third surface of the under-bump pattern is in direct physical contact with the interconnection portion of the first redistribution pattern, wherein the fourth surface of the under-bump pattern is in direct physical contact with the outer coupling terminal, and wherein the fourth surface of the under-bump pattern is embedded by the first insulating layer.

18. The semiconductor package of claim 17, wherein the fourth surface of the under-bump pattern is positioned at a first level that is higher than a second level of the bottommost surface of the first insulating layer.

19. The semiconductor package of claim 17, wherein an edge portion of the fourth surface of the under-bump pattern is covered by, and in direct contact with, the first insulating layer.

20. The semiconductor package of claim 17, wherein the first insulating layer comprises at least one of photo-sensitive polyimide, poly(benzoxazole), phenol-based polymers, or benzocyclobutene-based polymers.
